

MM9BZ2V0~MM9BZ75-HAF

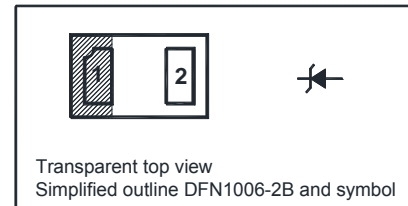
Silicon Planar Zener Diodes

Features

- Total power dissipation: max. 250 mW
- Small plastic package suitable for surface mounted design
- High reliability
- Halogen and Antimony Free(HAF), RoHS compliant

PINNING

PIN	DESCRIPTION
1	Cathode
2	Anode



Absolute Maximum Ratings ($T_a = 25^\circ\text{C}$)

Parameter	Symbol	Value	Unit
Total Device Dissipation	P_{tot}	250	mW
Junction and Storage Temperature Range	T_j, T_{stg}	- 65 to + 150	$^\circ\text{C}$

Characteristics at $T_a = 25^\circ\text{C}$

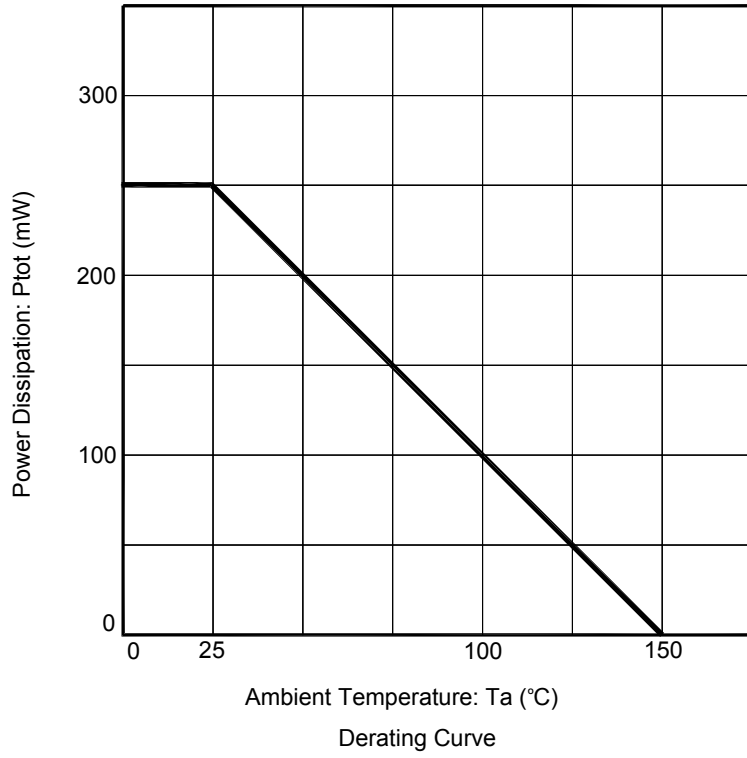
Parameter	Symbol	Max.	Unit
Forward Voltage at $I_F = 10 \text{ mA}$	V_F	0.9	V

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Type	Marking Code	Zener Voltage ¹⁾			Zener Impedance				Leakage Current	
		V _{ZT}		at I _{ZT}	Z _{ZT}	at I _{ZT}	Z _{ZK}	at I _{ZK}	I _R	at V _R
		Min. (V)	Max. (V)	(mA)	Max. (Ω)	(mA)	Max. (Ω)	(mA)	Max. (μA)	(V)
MM9BZ2V0	9H	1.8	2.15	5	100	5	-	-	120	0.5
MM9BZ2V2	9J	2.08	2.33	5	100	5	-	-	120	0.7
MM9BZ2V4	9K	2.2	2.6	5	100	5	1000	1	120	1
MM9BZ2V7	9L	2.5	2.9	5	100	5	1000	1	120	1
MM9BZ3V0	9M	2.8	3.2	5	100	5	1000	1	50	1
MM9BZ3V3	9N	3.1	3.5	5	95	5	1000	1	20	1
MM9BZ3V6	9P	3.4	3.8	5	90	5	1000	1	10	1
MM9BZ3V9	9Q	3.7	4.1	5	90	5	1000	1	5	1
MM9BZ4V3	9R	4	4.6	5	90	5	1000	1	5	1
MM9BZ4V7	9S	4.4	5	5	80	5	800	1	2	1
MM9BZ5V1	9T	4.8	5.4	5	60	5	500	1	2	1.5
MM9BZ5V6	9U	5.2	6	5	40	5	200	1	1	2.5
MM9BZ6V2	9V	5.8	6.6	5	10	5	100	1	1	3
MM9BZ6V8	9W	6.4	7.2	5	15	5	160	1	0.5	3.5
MM9BZ7V5	9X	7	7.9	5	15	5	160	1	0.5	4
MM9BZ8V2	9Y	7.7	8.7	5	15	5	160	1	0.5	5
MM9BZ9V1	9Z	8.5	9.6	5	15	5	160	1	0.5	6
MM9BZ10	0A	9.4	10.6	5	20	5	160	1	0.1	7
MM9BZ11	0B	10.4	11.6	5	20	5	160	1	0.1	8
MM9BZ12	0C	11.4	12.7	5	25	5	80	1	0.1	9
MM9BZ13	0D	12.4	14.1	5	30	5	80	1	0.1	10
MM9BZ15	0E	13.8	15.6	5	30	5	80	1	0.1	11
MM9BZ16	0F	15.3	17.1	2	40	2	80	1	0.1	12
MM9BZ18	0G	16.8	19.1	2	45	2	80	1	0.1	13
MM9BZ20	0H	18.8	21.2	2	55	2	100	1	0.1	15
MM9BZ22	0J	20.8	23.3	2	55	2	100	1	0.1	17
MM9BZ24	0K	22.8	25.6	2	70	2	120	1	0.1	19
MM9BZ27	0L	25.1	28.9	2	80	2	300	1	0.1	21
MM9BZ30	0M	28	32	2	80	2	300	1	0.1	23
MM9BZ33	0N	31	35	2	80	2	300	1	0.1	25
MM9BZ36	0P	34	38	2	90	2	500	1	0.1	27
MM9BZ39	0Q	37	41	2	130	2	500	1	2	30
MM9BZ43	0R	40	46	1	150	1	500	1	2	33
MM9BZ47	0S	44	50	1	170	1	500	1	2	36
MM9BZ51	0T	48	54	1	180	1	500	1	1	39
MM9BZ56	0U	52	60	1	200	1	500	1	1	43
MM9BZ62	0V	58	66	1	215	1	500	1	0.2	47
MM9BZ68	0W	64	72	1	240	1	500	1	0.2	52
MM9BZ75	0X	70	79	1	255	1	500	1	0.2	57

¹⁾ Tested with pulses tp = 20 ms.

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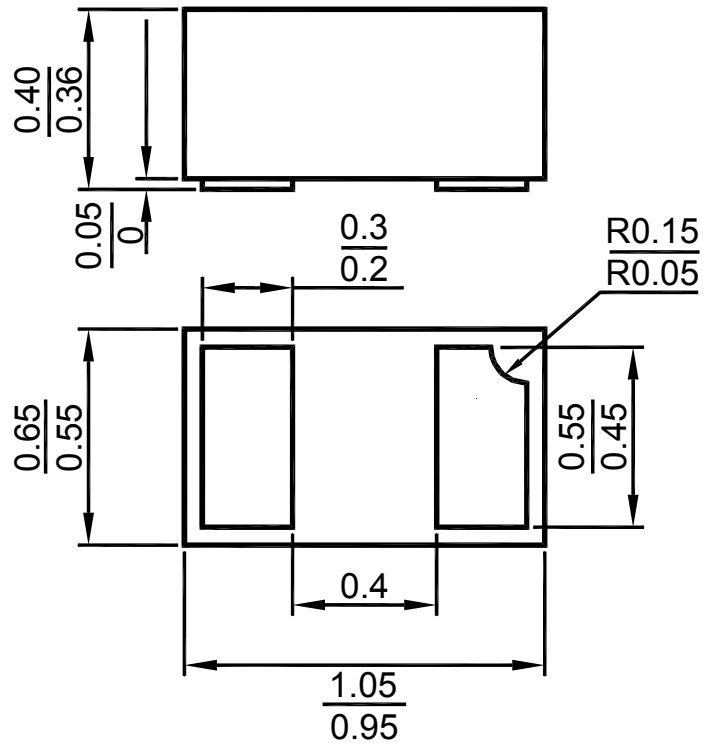


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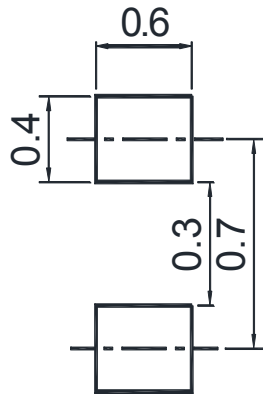
PACKAGE OUTLINE

Plastic surface mounted package

DFN1006-2B



Recommended Soldering Footprint



Packing information

Package	Tape Width (mm)	Pitch		Reel Size		Per Reel Packing Quantity
		mm	inch	mm	inch	
DFN1006-2B	8	4 ± 0.1	0.157 ± 0.004	178	7	5,000

TOP DYNAMIC

Dated: 24/06/2017 Rev: 01